



BSI Standards Publication

Test methods for electrical materials, printed board and other interconnection structures and assemblies

Part 5-502: General test methods for materials and assemblies —
Surface insulation resistance (SIR) testing of assemblies

National foreword

This British Standard is the UK implementation of EN IEC 61189-5-502:2021. It is identical to IEC 61189-5-502:2021.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic Assembly Technology.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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Amendments/corrigenda issued since publication

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English Version

Test methods for electrical materials, printed board and other
interconnection structures and assemblies - Part 5-502: General
test methods for materials and assemblies - Surface insulation
resistance (SIR) testing of assemblies
(IEC 61189-5-502:2021)

Méthodes d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 5-502: Méthodes d'essai générales pour
les matériaux et les ensembles - Essais de résistance
d'isolement en surface (RIS) des ensembles
(IEC 61189-5-502:2021)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen - Teil 5-
502: Allgemeine Prüfverfahren für Materialien und
Baugruppen - Prüfung des
Oberflächenisolationswiderstands (SIR) von Baugruppen
(IEC 61189-5-502:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

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The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-12-10
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-03-10

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 61189-1	NOTE	Harmonized as EN 61189-1
IEC 61189-3	NOTE	Harmonized as EN 61189-3
IEC 61189-5 (series)	NOTE	Harmonized as EN IEC 61189-5 (series)
IEC 61189-6	NOTE	Harmonized as EN 61189-6
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2
IEC 61249-2-7	NOTE	Harmonized as EN 61249-2-7
IEC 62137-4:2014	NOTE	Harmonized as EN 62137-4:2014 (not modified)
ISO 9001	NOTE	Harmonized as EN ISO 9001
ISO 9455-1	NOTE	Harmonized as EN 29455-1
ISO 9455-2	NOTE	Harmonized as EN ISO 9455-2

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	-	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	-
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60068-2-67	-	Environmental testing - Part 2-67: Tests - Test Cy: Damp heat, steady state, accelerated test primarily intended for components	EN 60068-2-67	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications	EN IEC 61190-1-3	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 5-502: General test methods for materials and assemblies –
Surface Insulation Resistance (SIR) testing of assemblies**

FOREWORD

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Draft	Report on voting
91/1646/CDV	91/1673/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.